

ABSTRACT OF THE DISCLOSURE

A wafer heat-treatment system for processing a wafer by a high-temperature heat-treatment process and cooling
5 the heat-treated wafer, comprises walls surrounding a closed space placing the wafer and having a hollow sealing a gas therein, and a pressure-regulating unit connecting to the hollow for regulating pressure in the hollow. Hence, the wafer heat-treatment system reduces power consumption
10 by heating lamps by carrying out an evacuating process before the high-temperature heat-treatment process, and shortens the time necessary for the cool down process by a pressurizing process that is carried out after the completion of the high-temperature heat-treatment process.

RECORDED - 100% - 00000000000000000000000000000000